

SOT1356-1

plastic, extremely thin fine-pitch ball grid array package, 28 terminals, 0.5 mm pitch, 2 mm x 4 mm x 0.5 mm body

5 June 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	XFPGA28
Package style descriptive code	XFPGA (extremely thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-03-2009
Manufacturer package code	SOT1356-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.9	2	2.1	mm
package width	3.9	4	4.1	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	28	-	



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2 Package outline

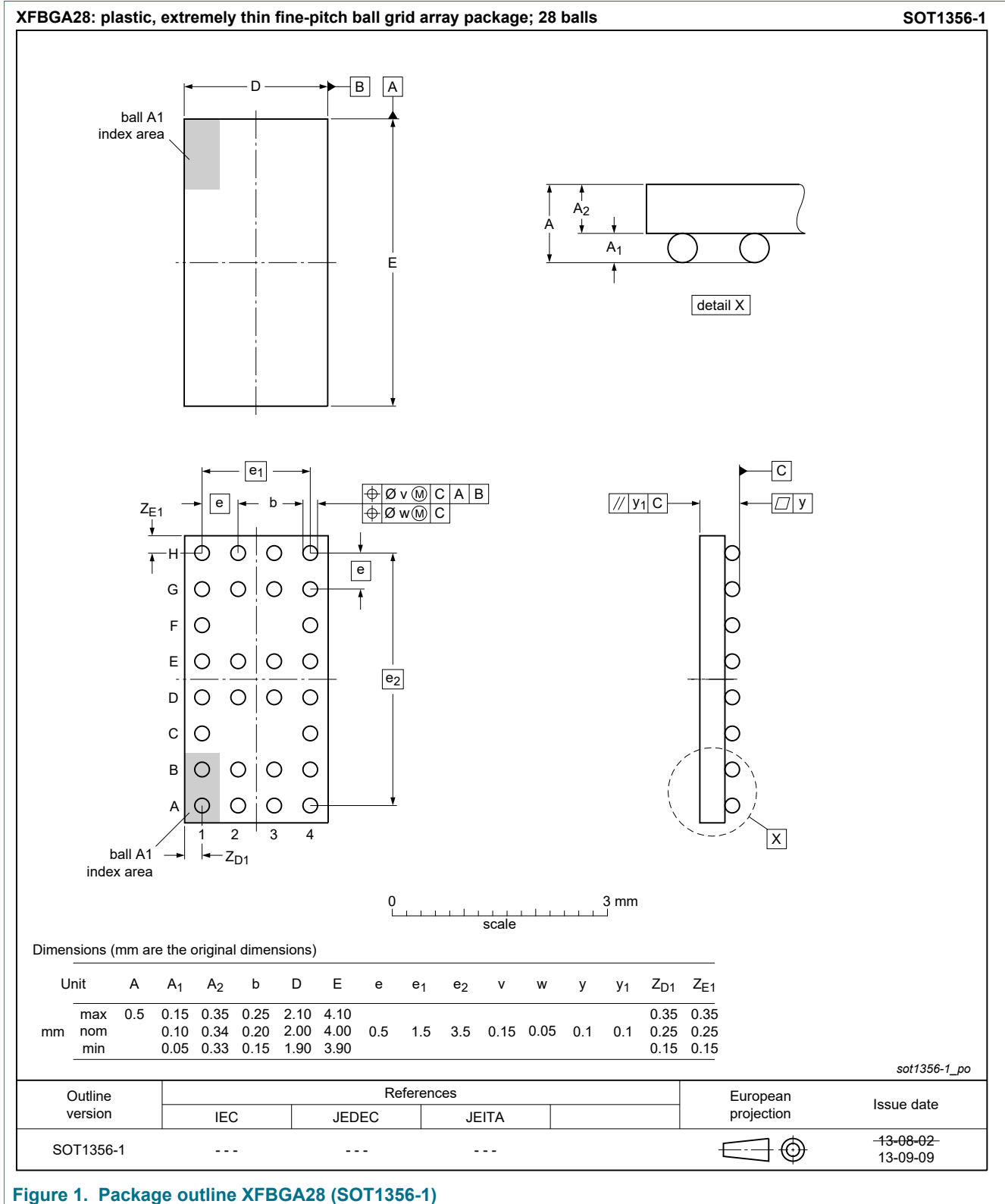


Figure 1. Package outline XFBGA28 (SOT1356-1)

3 Legal information

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